

# PS9506,PS9506L1,PS9506L2,PS9506L3

R08DS0018EJ0100 Rev.1.00 Nov 10, 2011

0.6 A OUTPUT CURRENT, HIGH CMR, IGBT GATE DRIVE, 8-PIN DIP PHOTOCOUPLER

#### DESCRIPTION

The PS9506, PS9506L1, PS9506L2 and PS9506L3 are optically coupled isolators containing a GaAlAs LED on the input side and a photo diode, a signal processing circuit and a power output transistor on the output side on one chip. The PS9506 Series is designed specifically for high common mode transient immunity (CMR) and high switching speed.

The PS9506 Series is suitable for driving IGBTs and MOS FETs.

The PS9506 Series is in a plastic DIP (Dual In-line Package).

The PS9506L1 is lead bending type for long creepage distance.

The PS9506L2 is lead bending type for long creepage distance (Gull-wing) for surface mount.

The PS9506L3 is lead bending type (Gull-wing) for surface mounting.

#### **FEATURES**

- Long creepage distance (8 mm MIN.: PS9506L1, PS9506L2)
- Peak output current (0.6 A MAX., 0.4 A MIN.)
- High speed switching ( $t_{PLH}$ ,  $t_{PHL} = 0.4 \mu s$  MAX.)
- High common mode transient immunity (CM<sub>H</sub>, CM<sub>L</sub> =  $\pm 25$  kV/ $\mu$ s MIN.)
- Embossed tape product: PS9506L2-E3, PS9506L3-E3: 1 000 pcs/reel
- Pb-Free product
- · Safety standards

<R>

- UL approved: No. E72422
- CSA approved: No. CA 101391 (CA5A, CAN/CSA-C22.2 60065, 60950)
- SEMKO approved: No. 1115598
- DIN EN60747-5-2 (VDE0884 Part2) approved: No. 40024069 (Option)

# PIN CONNECTION (Top View) 8 7 6 5 2. Anode 3. Cathode 4. NC 5. Vee 6. Vo 7. NC 1 2 3 4 8. Vcc

#### **APPLICATIONS**

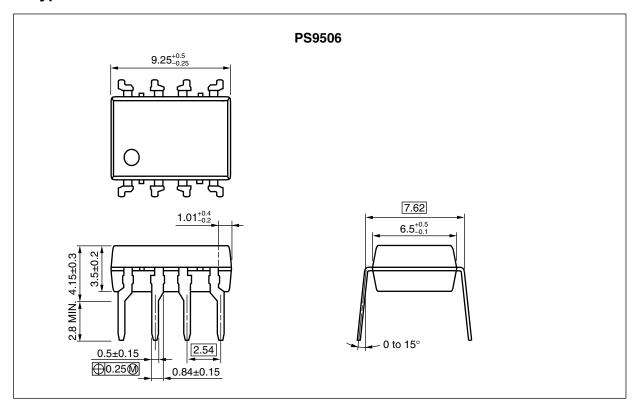
- IGBT, Power MOS FET Gate Driver
- Industrial inverter
- IH (Induction Heating)

The mark <R> shows major revised points.

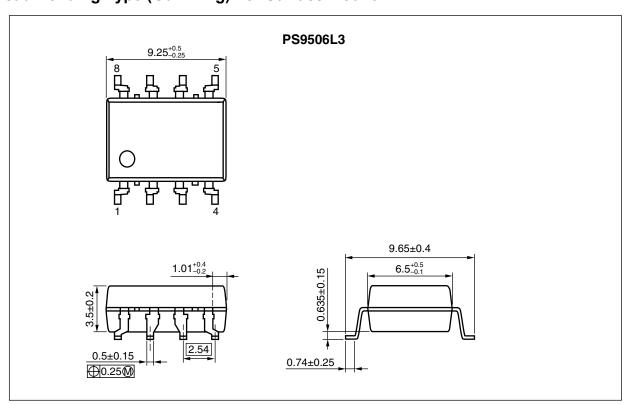
The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

## PACKAGE DIMENSIONS (UNIT: mm)

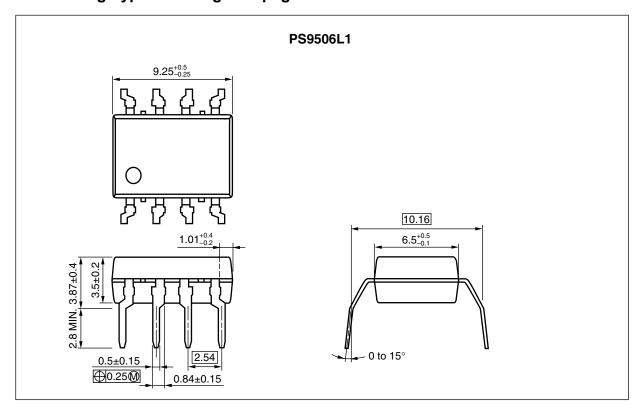
## **DIP Type**



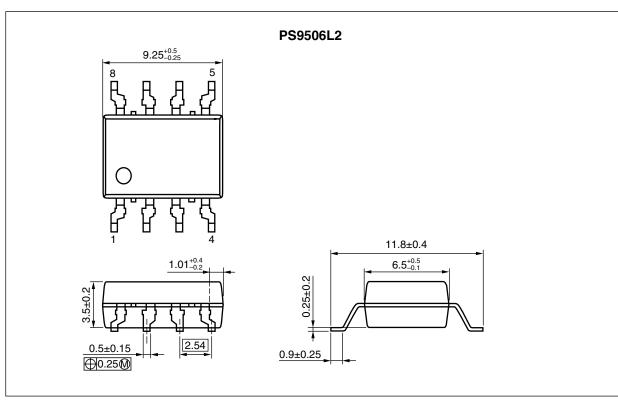
## Lead Bending Type (Gull-wing) For Surface Mount



## **Lead Bending Type For Long Creepage Distance**



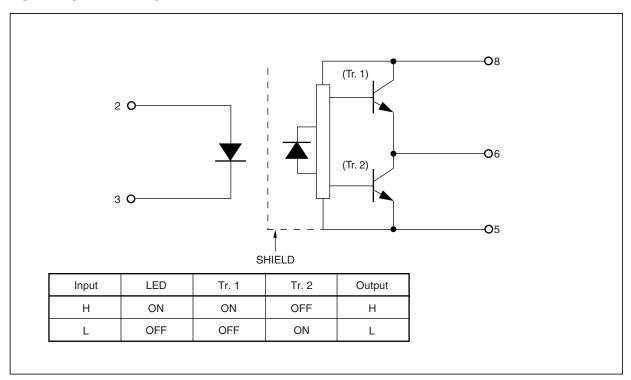
## Lead Bending Type (Gull-wing) For Long Creepage Distance (Surface Mount)



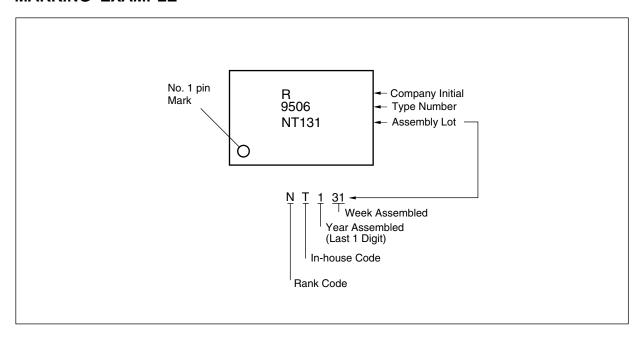
## PHOTOCOUPLER CONSTRUCTION

Parameter	PS9506, PS9506L3	PS9506L1, PS9506L2	
Air Distance (MIN.)	7 mm	8 mm	
Outer Creepage Distance (MIN.)	7 mm	8 mm	
Isolation Distance (MIN.)	0.4 mm	0.4 mm	

## **FUNCTIONAL DIAGRAM**



### <R> MARKING EXAMPLE



## <R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number <sup>*1</sup>
PS9506	PS9506-AX	Pb-Free	50 Magazine Cases	Standard	PS9506
PS9506L1	PS9506L1-AX	(Ni/Pd/Au)		products	PS9506L1
PS9506L2	PS9506L2-AX			(UL, CSA, SEMKO	PS9506L2
PS9506L3	PS9506L3-AX			approved)	PS9506L3
PS9506L2-E3	PS9506L2-E3-AX		Embossed Tape		PS9506L2
PS9506L3-E3	PS9506L3-E3-AX		1 000 pcs/reel		PS9506L3
PS9506-V	PS9506-V-AX		50 Magazine Cases	DIN EN60747-5-2	PS9506
PS9506L1-V	PS9506L1-V-AX			(VDE0884 Part2)	PS9506L1
PS9506L2-V	PS9506L2-V-AX			approved	PS9506L2
PS9506L3-V	PS9506L3-V-AX			(Option)	PS9506L3
PS9506L2-V-E3	PS9506L2-V-E3-AX		Embossed Tape	]	PS9506L2
PS9506L3-V-E3	PS9506L3-V-E3-AX		1 000 pcs/reel		PS9506L3

Note: \*1. For the application of the Safety Standard, following part number should be used.

## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	I <sub>F</sub>	25	mA
	Peak Transient	I <sub>F (TRAN)</sub>	1.0	Α
	Forward Current			
	(Pulse Width < 1 $\mu$ s)			
	Reverse Voltage	$V_R$	5	V
	Power Dissipation *1	$P_D$	45	mW
Detector	High Level Peak	I <sub>OH (PEAK)</sub>	0.6	Α
	Output Current *2			
	Low Level Peak	I <sub>OL (PEAK)</sub>	0.6	Α
	Output Current *2			
	Supply Voltage	$(V_{CC}-V_{EE})$	0 to 35	V
	Output Voltage	Vo	0 to V <sub>CC</sub>	V
	Power Dissipation *3	Pc	250	mW
Isolation \		BV	5 000	Vr.m.s.
Operating Frequency *5		f	50	kHz
Operating Ambient Temperature		T <sub>A</sub>	-40 to +110	°C
Storage Temperature		T <sub>stg</sub>	-55 to +125	°C

Notes: \*1. Reduced to 1.2 mW/ $^{\circ}$ C at  $T_A$  = 85 $^{\circ}$ C or more.

## RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	(V <sub>CC</sub> -V <sub>EE</sub> )	10		30	V
Forward Current (ON)	I <sub>F (ON)</sub>	8		12	mA
Forward Voltage (OFF)	V <sub>F (OFF)</sub>	-2		0.8	V
Operating Ambient Temperature	T <sub>A</sub>	-40		110	°C

<sup>\*2.</sup> Maximum pulse width = 10  $\mu$ s, Maximum duty cycle = 0.2%

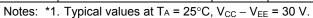
<sup>\*3.</sup> Reduced to 5.5 mW/ $^{\circ}$ C at  $T_A$  = 75 $^{\circ}$ C or more.

<sup>\*4.</sup> AC voltage for 1 minute at  $T_A$  = 25°C, RH = 60% between input and output. Pins 1-4 shorted together, 5-8 shorted together.

<sup>\*5.</sup>  $I_{OH (PEAK)} \le 0.4 \text{ A } (\le 2.0 \ \mu\text{s}), \ I_{OL (PEAK)} \le 0.4 \text{ A } (\le 2.0 \ \mu\text{s})$ 

# ELECTRICAL CHARACTERISTICS ( $T_A$ = -40 to +110°C, $V_{CC}$ = 10 to 30 V, $I_{F (ON)}$ = 8 to 12 mA, $V_{F (OFF)}$ = -2 to 0.8 V, $V_{EE}$ = GND, unless otherwise specified)

	Parameter		Conditions	MIN.	TYP.*1	MAX.	Unit
Diode	Forward Voltage V <sub>F</sub>		I <sub>F</sub> = 10 mA, T <sub>A</sub> = 25°C	1.2	1.56	1.8	V
	Reverse Current	$I_R$	V <sub>R</sub> = 3 V, T <sub>A</sub> = 25°C			10	μΑ
	Input Capacitance	C <sub>IN</sub>	$f = 1 \text{ MHz}, V_F = 0 \text{ V}, T_A = 25^{\circ}\text{C}$		30		pF
Detector	High Level Output Current	I <sub>OH</sub>	$V_{\rm O} = (V_{\rm CC} - 4  V)^{*2}$	0.2			Α
			$V_{\rm O} = (V_{\rm CC} - 10 \text{ V})^{*3}$	0.4	0.5		
	Low Level Output Current	I <sub>OL</sub>	$V_{O} = (V_{EE} + 2.5 \text{ V})^{*2}$	0.2	0.4		Α
			$V_{O} = (V_{EE} + 10 \text{ V})^{*3}$	0.4	0.5		
	High Level Output Voltage	V <sub>OH</sub>	$I_0 = -100 \text{ mA}^{*4}$	V <sub>CC</sub> – 4.0	V <sub>CC</sub> – 1.8		V
	Low Level Output Voltage	$V_{OL}$	I <sub>O</sub> = 100 mA		0.4	1.0	V
	High Level Supply Current	I <sub>CCH</sub>	$I_F = 10 \text{ mA}, I_O = 0 \text{ mA}$		0.7	3.0	mA
	Low Level Supply Current		$I_F = 0 \text{ mA}, I_O = 0 \text{ mA}$		1.2	3.0	mA
Coupled	Threshold Input Current	I <sub>FLH</sub>	$I_{O} = 0 \text{ mA}, V_{O} > 5 \text{ V}$			7.0	mA
	$(L \rightarrow H)$						
	Threshold Input Voltage	$V_{FHL}$	$I_{O} = 0 \text{ mA}, V_{O} < 5 \text{ V}$	0.8			V
	$(H \rightarrow L)$						
	Isolation Capacitance	$C_{\text{I-O}}$	$V_F = 0 V, f = 1 MHz, T_A = 25^{\circ}C$		0.7		pF



<sup>\*2.</sup> Maximum pulse width = 50  $\mu$ s, Maximum duty cycle = 0.5%.



<sup>\*3.</sup> Maximum pulse width = 10  $\mu$ s, Maximum duty cycle = 0.2%.

<sup>\*4.</sup> V<sub>OH</sub> is measured with the DC load current in this testing.

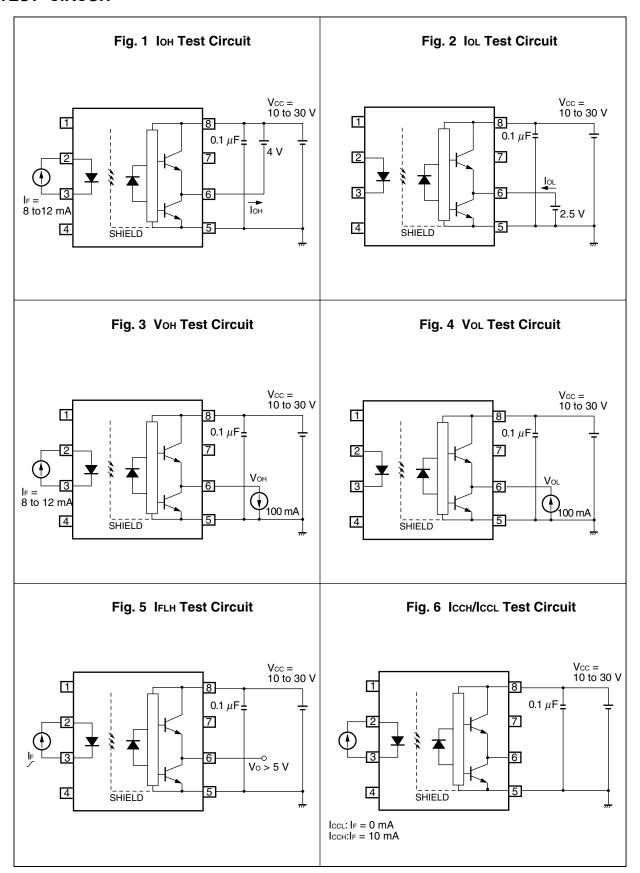
# SWITCHING CHARACTERISTICS ( $T_A$ = -40 to +110°C, $V_{CC}$ = 10 to 30 V, $I_{F (ON)}$ = 8 to 12 mA, $V_{F (OFF)}$ = -2 to 0.8 V, $V_{EE}$ = GND, unless otherwise specified)

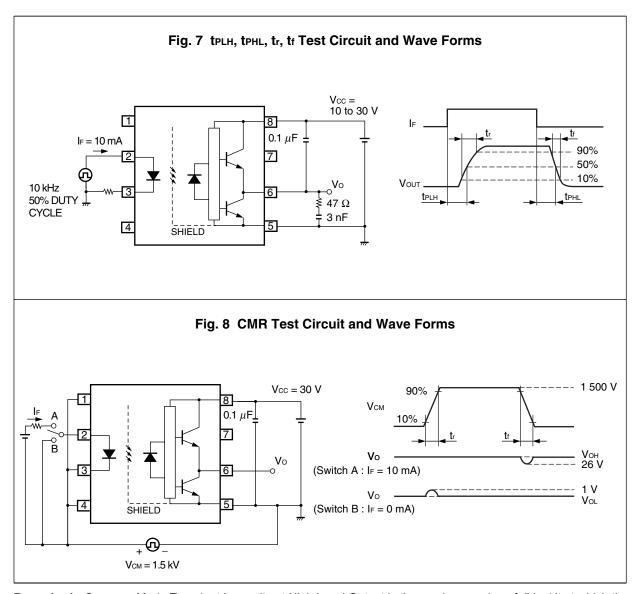
Parameter	Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit
Propagation Delay Time $(L \rightarrow H)$	t <sub>PLH</sub>	$R_g = 47 \Omega, C_g = 3 nF,$	0.05	0.18	0.4	μs
Propagation Delay Time $(H \rightarrow L)$	t <sub>PHL</sub>	f = 10 kHz,	0.05	0.18	0.4	μs
Pulse Width Distortion (PWD)	t <sub>PHL</sub> -t <sub>PLH</sub>	Duty Cycle = 50% <sup>*2</sup> ,			0.25	μs
Propagation Delay Time (Difference Between Any Two Products)	t <sub>PHL</sub> —t <sub>PLH</sub>	I <sub>F</sub> = 10 mA, V <sub>CC</sub> = 30 V	-0.3		0.3	μs
Rise Time	t <sub>r</sub>			50		ns
Fall Time	t <sub>f</sub>			50		ns
Common Mode Transient Immunity at High Level Output	CM <sub>H</sub>	$T_A = 25^{\circ}\text{C}, I_F = 10 \text{ mA},$ $V_{CC} = 30 \text{ V}, V_{CM} = 1.5 \text{ kV},$ $V_{O \text{ (MIN.)}} = 26 \text{ V}$	25			kV/μs
Common Mode Transient Immunity at Low Level Output	CM <sub>L</sub>	$T_A = 25^{\circ}\text{C}, I_F = 0 \text{ mA},$ $V_{CC} = 30 \text{ V}, V_{CM} = 1.5 \text{ kV},$ $V_{O \text{ (MAX.)}} = 1 \text{ V}$	25			kV/μs

Notes: \*1. Typical values at  $T_A = 25^{\circ}C$ ,  $V_{CC} - V_{EE} = 30 \text{ V}$ .

<sup>\*2.</sup> This load condition is equivalent to the IGBT load at 1 200 V/25 A.

## <R> TEST CIRCUIT

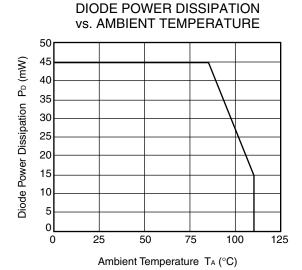


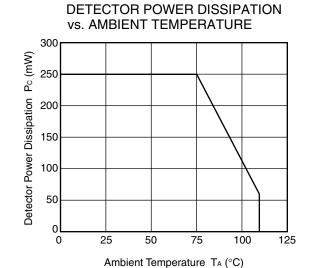


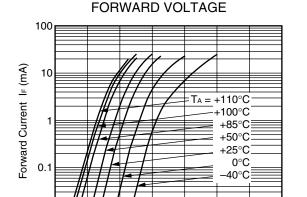
**Remarks 1.** Common Mode Transient Immunity at High Level Output is the maximum value of  $dV_{CM}/dt$  at which the output remains High Level (e.g.  $V_O > 26 \text{ V}$ ).

2. Common Mode Transient Immunity at Low Level Output is the maximum value of  $dV_{CM}/dt$  at which the output remains Low Level (e.g.  $V_O < 1.0 \text{ V}$ ).

## <R> TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25°C, unless otherwise specified)



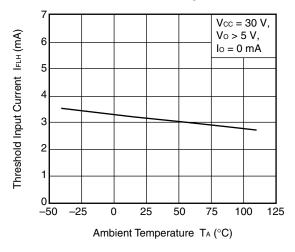


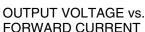


0.01

FORWARD CURRENT vs.

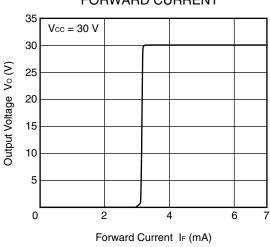
THRESHOLD INPUT CURRENT vs. AMBIENT TEMPERATURE



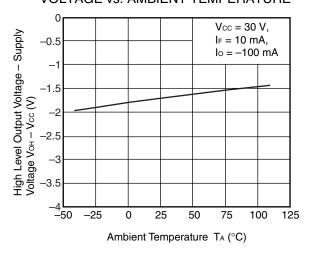


Forward Voltage V<sub>F</sub> (V)

1.6

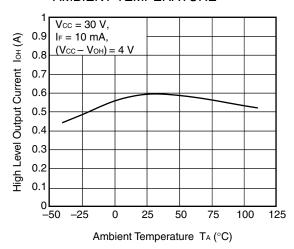


# HIGH LEVEL OUTPUT VOLTAGE – SUPPLY VOLTAGE vs. AMBIENT TEMPERATURE

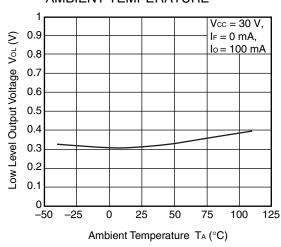


Remark The graphs indicate nominal characteristics.

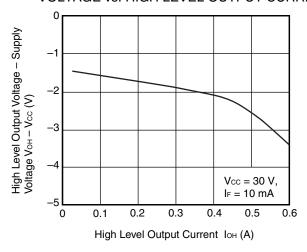
# HIGH LEVEL OUTPUT CURRENT vs. AMBIENT TEMPERATURE



## LOW LEVEL OUTPUT VOLTAGE vs. AMBIENT TEMPERATURE

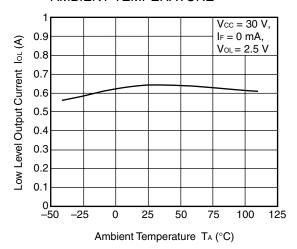


# HIGH LEVEL OUTPUT VOLTAGE – SUPPLY VOLTAGE vs. HIGH LEVEL OUTPUT CURRENT

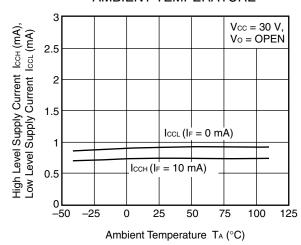


**Remark** The graphs indicate nominal characteristics.

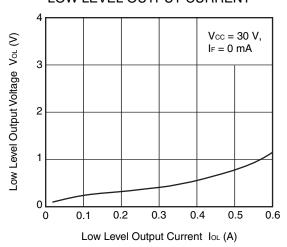
# LOW LEVEL OUTPUT CURRENT vs. AMBIENT TEMPERATURE



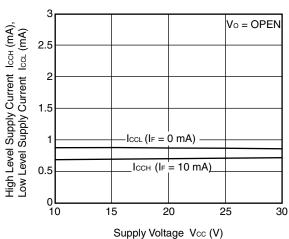
#### SUPPLY CURRENT vs. AMBIENT TEMPERATURE



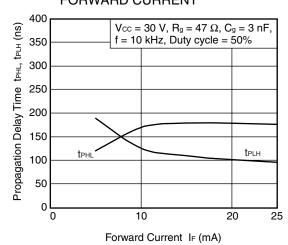
# LOW LEVEL OUTPUT VOLTAGE vs. LOW LEVEL OUTPUT CURRENT



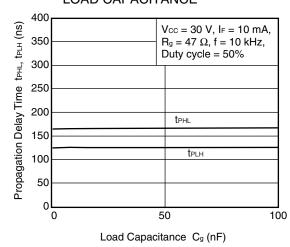
# SUPPLY CURRENT vs. SUPPLY VOLTAGE



# PROPAGATION DELAY TIME vs. FORWARD CURRENT

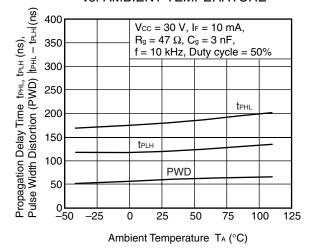


# PROPAGATION DELAY TIME vs. LOAD CAPACITANCE

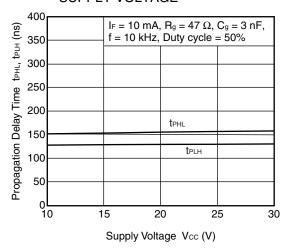


Remark The graphs indicate nominal characteristics.

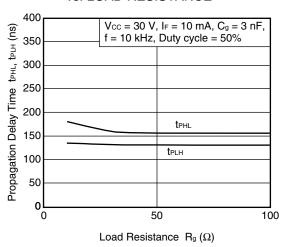
# PROPAGATION DELAY TIME, PULSE WIDTH DISTORTION vs. AMBIENT TEMPERATURE



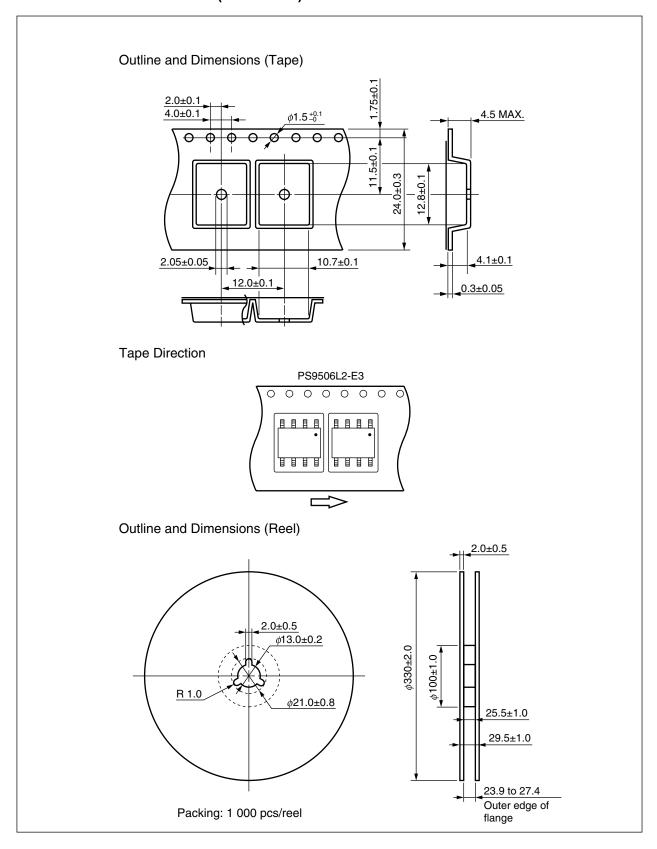
# PROPAGATION DELAY TIME vs. SUPPLY VOLTAGE

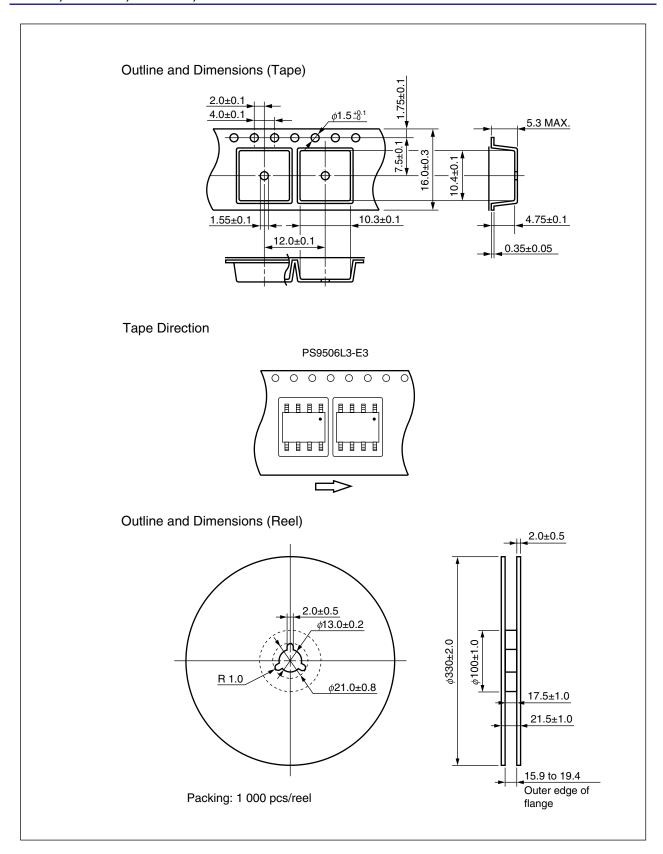


# PROPAGATION DELAY TIME vs. LOAD RESISTANCE

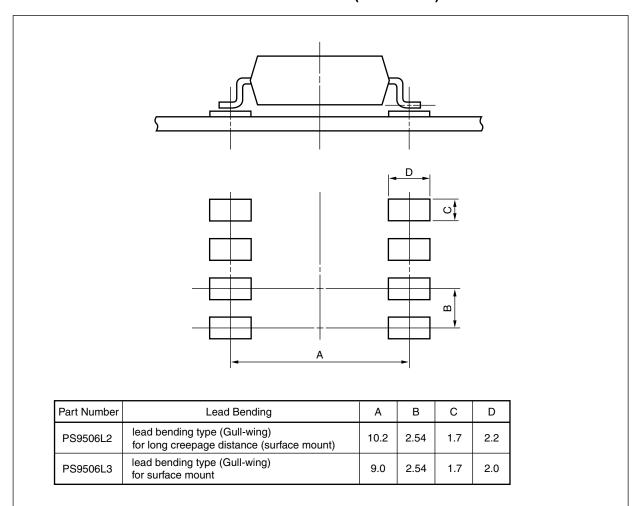


## TAPING SPECIFICATIONS (UNIT: mm)





## <R> RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



#### <R> NOTES ON HANDLING

- 1. Recommended soldering conditions
  - (1) Infrared reflow soldering

Peak reflow temperature 260°C or below (package surface temperature)

Time of peak reflow temperature 10 seconds or less 60 seconds or less

Time of temperature higher than 220°C

Time to preheat temperature from 120 to 180°C 120±30 s

Number of reflows

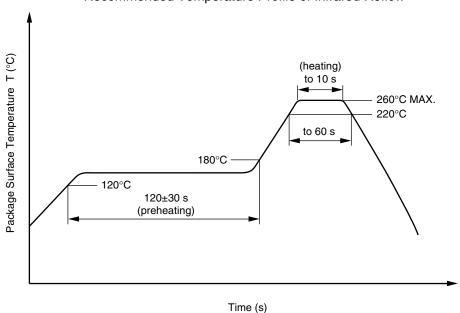
Flux

Three Rosin flux containing small amount of chlorine (The flux

with a maximum chlorine content of 0.2 Wt% is

recommended.)

#### Recommended Temperature Profile of Infrared Reflow



#### (2) Wave soldering

Temperature 260°C or below (molten solder temperature)

Time 10 seconds or less

Preheating conditions 120°C or below (package surface temperature)

Number of times One (Allowed to be dipped in solder including plastic mold portion.)

Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

#### (3) Soldering by Soldering Iron

Peak Temperature (lead part temperature) 350°C or below

Time (each pins) 3 seconds or less

Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

#### (4) Cautions

 Fluxes Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

#### 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

#### <R> USAGE CAUTIONS

- 1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
- 2. Board designing
  - (1) By-pass capacitor of more than 0.1  $\mu$ F is used between  $V_{CC}$  and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
  - (2) When designing the printed wiring board, ensure that the pattern of the IGBT collectors/emitters is not too close to the input block pattern of the photocoupler.
    - If the pattern is too close to the input block and coupling occurs, a sudden fluctuation in the voltage on the IGBT output side might affect the photocoupler's LED input, leading to malfunction or degradation of characteristics. (If the pattern needs to be close to the input block, to prevent the LED from lighting during the off state due to the abovementioned coupling, design the input-side circuit so that the bias of the LED is reversed, within the range of the recommended operating conditions, and be sure to thoroughly evaluate operation.)
  - (3) Pins 1, 4 (which is an NC\*1 pin) can either be connected directly to the GND pin on the LED side or left open. Also, Pin 7 (which is an NC\*1 pin) can either be connected directly to the GND pin on the detector side or left open.
    - Unconnected pins should not be used as a bypass for signals or for any other similar purpose because this may degrade the internal noise environment of the device.
    - Note: \*1. NC: Non-Connection (No Connection).
- 3. Make sure the rise/fall time of the forward current is 0.5  $\mu$ s or less.
- **4.** In order to avoid malfunctions, make sure the rise/fall slope of the supply voltage is  $3 \text{ V}/\mu\text{s}$  or less.
- **5.** Avoid storage at a high temperature and high humidity.

## <R> SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Spec.	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/110/21	
Dielectric strength			
maximum operating isolation voltage	$U_IORM$	1 130	$V_{peak}$
Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr}$ = 1.6 × $U_{IORM.}$ , $P_d$ < 5 pC	$U_pr$	1 808	$V_{peak}$
Test voltage (partial discharge test, procedure b for all devices)	U <sub>pr</sub>	2 119	V <sub>peak</sub>
$U_{pr} = 1.875 \times U_{IORM.}, P_d < 5 pC$			
Highest permissible overvoltage	$U_TR$	8 000	$V_{peak}$
Degree of pollution (DIN EN 60664-1 VDE0110 Part 1)		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303 Part 11))	CTI	175	
Material group (DIN EN 60664-1 VDE0110 Part 1)		III a	
Storage temperature range	$T_{stg}$	-55 to +125	°C
Operating temperature range	T <sub>A</sub>	-40 to +110	Ŝ
Isolation resistance, minimum value			
$V_{IO} = 500 \text{ V dc at T}_{A} = 25^{\circ}\text{C}$	Ris MIN.	10 <sup>12</sup>	Ω
$V_{IO}$ = 500 V dc at T <sub>A</sub> MAX. at least 100°C	Ris MIN.	10 <sup>11</sup>	Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal			
derating curve)			
Package temperature	Tsi	175	°C
Current (input current I <sub>F</sub> , Psi = 0)	lsi	400	mA
Power (output or total power dissipation)	Psi	700	mW
Isolation resistance			
$V_{IO}$ = 500 V dc at $T_A$ = Tsi	Ris MIN.	10 <sup>9</sup>	Ω

#### Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
  - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

## **Revision History**

## PS9506,PS9506L1,PS9506L2,PS9506L3 Data Sheet

		Description		
Rev.	Date	Page	Summary	
0.01	Aug 19, 2010	-	First edition issued	
1.00	Nov 10, 2011	Throughout	Preliminary Data Sheet → Data Sheet	
		Throughout	Safety standards approved	
		p.4	Modification of MARKING EXAMPLE	
		p.5	Addition of ORDERING INFORMATION	
		p.7	Modification of ELECTRICAL CHARACTERISTICS	
		pp.9, 10	Addition of TEST CIRCUIT	
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		p.19	Addition of SPECIFICATION OF VDE MARKS LICENSE DOCUMENT	

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Arcadiastrasse 10, 40472 Düsseldorf, Germany Tel: +49-211-65030, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.
7th Floor, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100083, P.R.China
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